

In re Patent Application of:
BYUN, II ET AL.
Serial No. 10/522,049
Filing Date: JANUARY 20, 2005

In the Claims:

1. (Currently Amended) A method for connecting microcircuits comprising ~~the steps of:~~

- (a) ~~generating~~ providing an insulating resin solution;
- (b) applying the insulating resin solution to each circuit board having circuit patterns;
- (c) aligning the circuit boards to face each other so that electrodes of the circuit boards face each other, in order to connect the corresponding electrodes of the circuit patterns formed in each circuit board;
- (d) positioning an anisotropic conductive adhesive between the circuit boards;
- (e) heating the circuit boards; and
- (f) applying a predetermined pressure to a side of each circuit board opposite the anisotropic conductive adhesive an-
~~opponent side to a side applied by the anisotropic conduction-~~
adhesive so that corresponding electrodes are connected to each other.

2. (Currently Amended) The method of claim 1, wherein in the (a) step said insulating resin solution is prepared by dissolving a thermoplastic resin having a softening point in the range of 60 to 150°C or a compound of the thermoplastic resin into a ~~soluble~~ solvent.

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3. (Original) The method of claim 2, wherein the thermoplastic resin is selected from the group of consisting of polyethylene resin, ethylene copolymer resin, ethylene vinyl acetate copolymer resin, ethylene-acrylic acid copolymer resin, ethylene acrylic acid ester copolymer resin, poly amide resin, poly ester resin, styrene butadiene copolymer resin, ethylene-propylene copolymer resin, acrylic acid ester rubber, acrylonitrile-butadiene copolymer resin, phenoxy resin, thermoplastic epoxy resin, poly urethane resin, poly vinyl acetal resin and poly vinyl butilal resin.

4. (Currently Amended) The method of claim1, wherein in the (a) step said insulating resin solution is prepared by dissolving thermoplastic resin having a softening point in the range of 80 to 120°C or a compound of the thermoplastic resin into a soluble solvent.

5. (Currently Amended) The method of claim 1, wherein in the (b) step said insulating resin solution produces a film layer ~~has~~ having a thickness of 0.1 to 5μm on the circuit board.

6. (Currently Amended) The method of claim 1, wherein in the (b) step said insulating resin solution produces a film layer ~~has~~ having a thickness of 0.3 to 3μm on the circuit board.

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7. (Original) The method of claim 1, wherein the anisotropic conductive adhesive includes an insulating component, and conductive particles dispersed in the insulating component.

8. (Currently Amended) The method of claim 1, wherein in the (b) step said insulating resin solution ~~insulating film-layer~~ is formed on a plain portion and a side portion of the circuit patterns and a bottom portion of the circuit board.

9. (Currently Amended) The method of claim 1, wherein in the (b) step said insulating resin solution ~~insulating film-layer~~ is formed on a side portion of the circuit pattern and a bottom portion of the circuit board.

Claims 10-17 (Cancelled).